

## Maximum Ratings @T<sub>A</sub> = 25°C unless otherwise specified

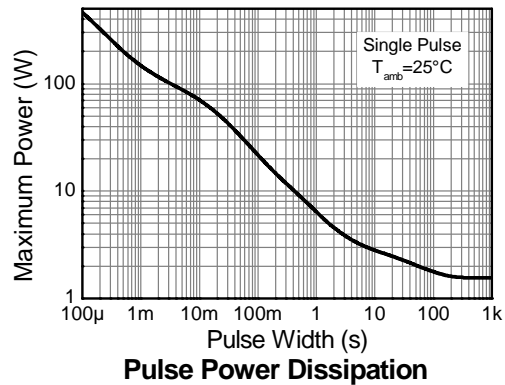
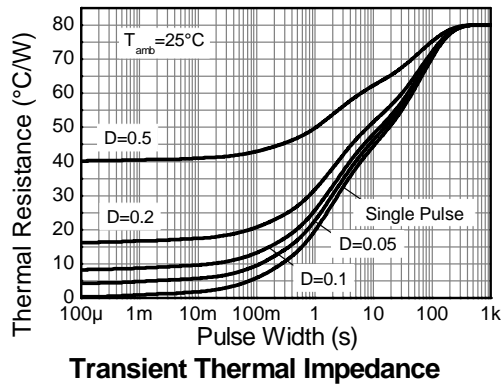
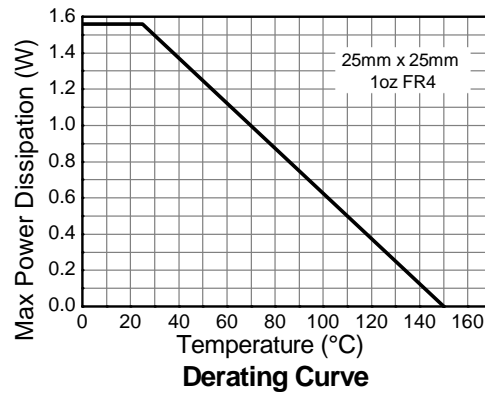
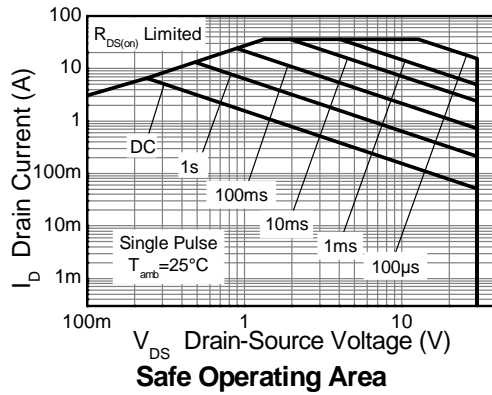
Characteristic			Symbol	Value	Unit
Drain-Source voltage			V <sub>DSS</sub>	30	V
Gate-Source voltage			V <sub>GS</sub>	±20	V
Continuous Drain current	V <sub>GS</sub> = 10V	(Note 3)	I <sub>D</sub>	8.5	A
		T <sub>A</sub> = 70°C (Note 3)		6.8	
		(Note 2)		6.4	
Pulsed Drain current	V <sub>GS</sub> = 10V	(Note 4)	I <sub>DM</sub>	36	A
Continuous Source current (Body diode)		(Note 3)	I <sub>S</sub>	4.5	A
Pulsed Source current (Body diode)		(Note 4)	I <sub>SM</sub>	36	A

## Thermal Characteristics @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic		Symbol	Value	Unit
Power dissipation	(Note 2)	P <sub>D</sub>	1.6	W
	(Note 3)		12.5	
Linear derating factor	(Note 3)		2.8	mW/°C
	(Note 3)		22.2	
Thermal Resistance, Junction to Ambient	(Note 2)	R <sub>θJA</sub>	80	°C/W
	(Note 3)		45	
Thermal Resistance, Junction to Lead	(Note 5)	R <sub>θJL</sub>	35	°C/W
Operating and storage temperature range		T <sub>J</sub> , T <sub>STG</sub>	-55 to 150	°C

- Notes:
- For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
  - Same as note (2), except the device is measured at t ≤ 10 sec.
  - Same as note (2), except the device is pulsed with D= 0.02 and pulse width 300 μs. The pulse current is limited by the maximum junction temperature.
  - Thermal resistance from junction to solder-point (at the end of the drain lead): the device is operating in a steady-state condition.

## Thermal Characteristics

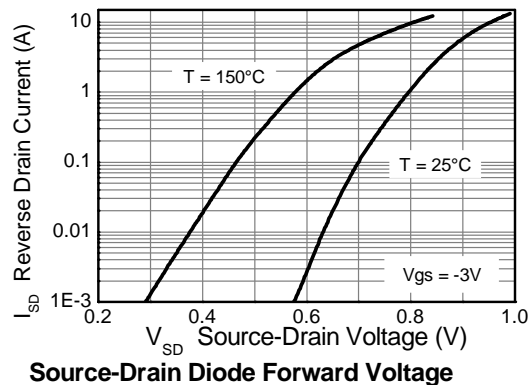
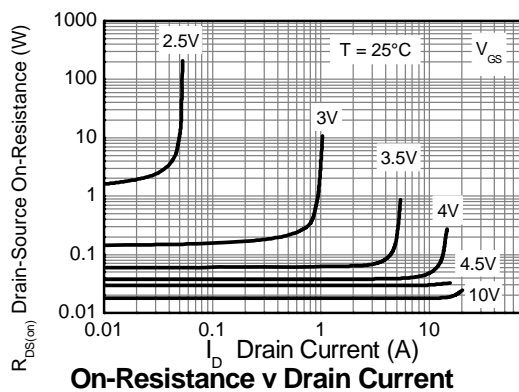
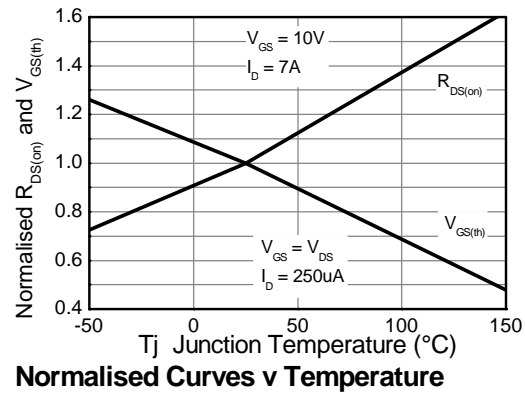
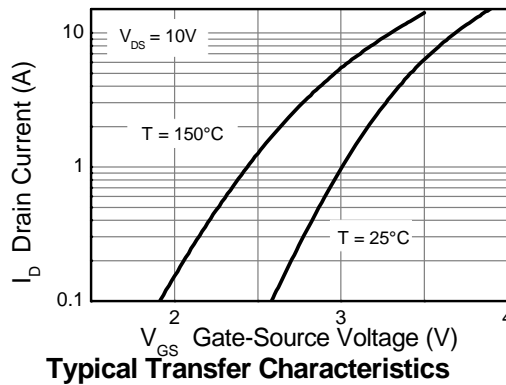
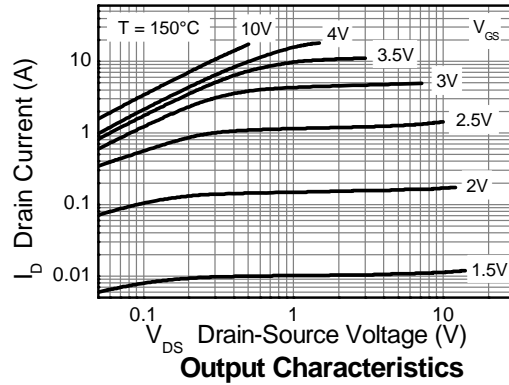
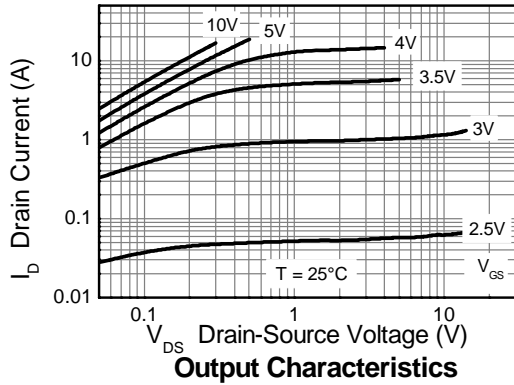


## Electrical Characteristics @T<sub>A</sub> = 25°C unless otherwise specified

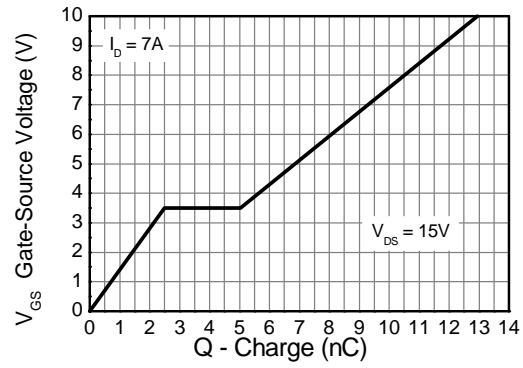
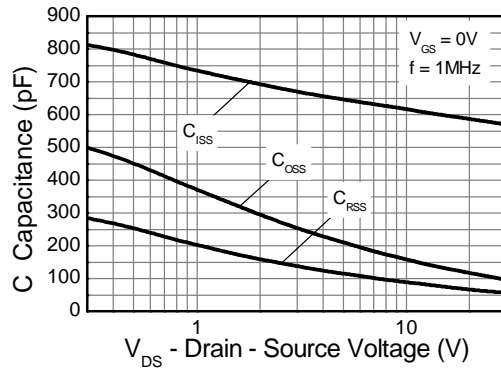
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	30	—	—	V	I <sub>D</sub> = 250μA, V <sub>GS</sub> = 0V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	—	—	0.5	μA	V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V
Gate-Source Leakage	I <sub>GSS</sub>	—	—	±100	nA	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V
ON CHARACTERISTICS						
Gate Threshold Voltage	V <sub>GS(th)</sub>	1.0	—	3.0	V	I <sub>D</sub> = 250μA, V <sub>DS</sub> = V <sub>GS</sub>
Static Drain-Source On-Resistance (Note 6)	R <sub>DS (ON)</sub>	—	—	0.024	Ω	V <sub>GS</sub> = 10V, I <sub>D</sub> = 7.0A
				0.036		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 6.0A
Forward Transconductance (Notes 6 & 7)	g <sub>fs</sub>	—	16.5	—	S	V <sub>DS</sub> = 15V, I <sub>D</sub> = 7.1A
Diode Forward Voltage (Note 6)	V <sub>SD</sub>	—	0.82	1.2	V	I <sub>S</sub> = 1.7A, V <sub>GS</sub> = 0V
Reverse recovery time (Note 7)	t <sub>rr</sub>		12	—	ns	I <sub>S</sub> = 2.2A, di/dt= 100A/μs
Reverse recovery charge (Note 7)	Q <sub>rr</sub>	—	4.8	—	nC	
DYNAMIC CHARACTERISTICS (Note 7)						
Input Capacitance	C <sub>iss</sub>	—	608	—	pF	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 0V f= 1MHz
Output Capacitance	C <sub>oss</sub>	—	132	—	pF	
Reverse Transfer Capacitance	C <sub>rss</sub>	—	71	—	pF	
Total Gate Charge	Q <sub>g</sub>	—	6.3	—	nC	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 4.5V I <sub>D</sub> = 7A
Total Gate Charge	Q <sub>g</sub>	—	12.9	—	nC	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 10V I <sub>D</sub> = 7A
Gate-Source Charge	Q <sub>gs</sub>	—	2.5	—	nC	
Gate-Drain Charge	Q <sub>gd</sub>	—	2.5	—	nC	
Turn-On Delay Time (Note 8)	t <sub>D(on)</sub>	—	2.9	—	ns	V <sub>DD</sub> = 15V, V <sub>GS</sub> = 10V I <sub>D</sub> = 1A, R <sub>G</sub> ≐ 6.0Ω
Turn-On Rise Time (Note 8)	t <sub>r</sub>	—	3.3	—	ns	
Turn-Off Delay Time (Note 8)	t <sub>D(off)</sub>	—	16	—	ns	
Turn-Off Fall Time (Note 8)	t <sub>f</sub>	—	8	—	ns	

- Notes:
6. Measured under pulsed conditions. Pulse width ≤ 300μs; duty cycle ≤ 2%
  7. For design aid only, not subject to production testing.
  8. Switching characteristics are independent of operating junction temperatures.

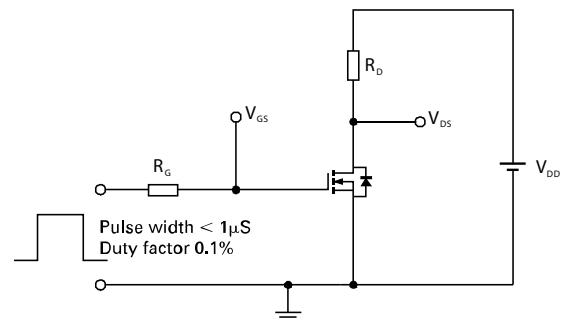
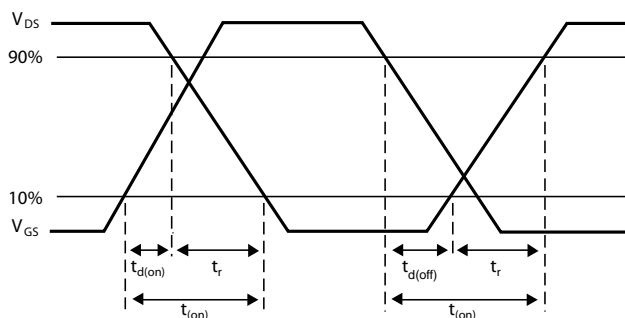
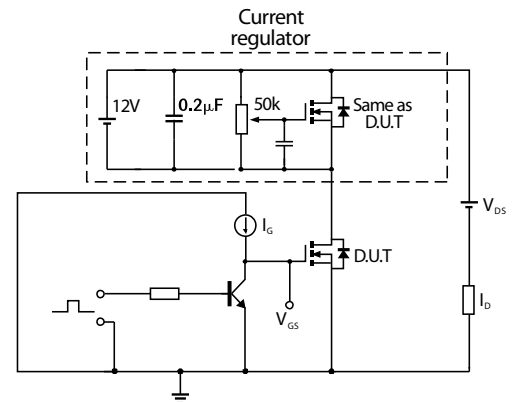
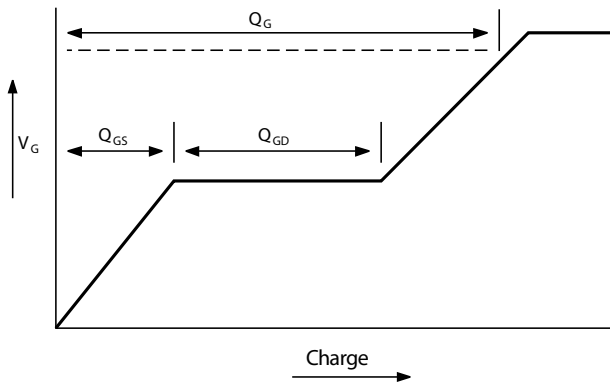
## Typical Characteristics



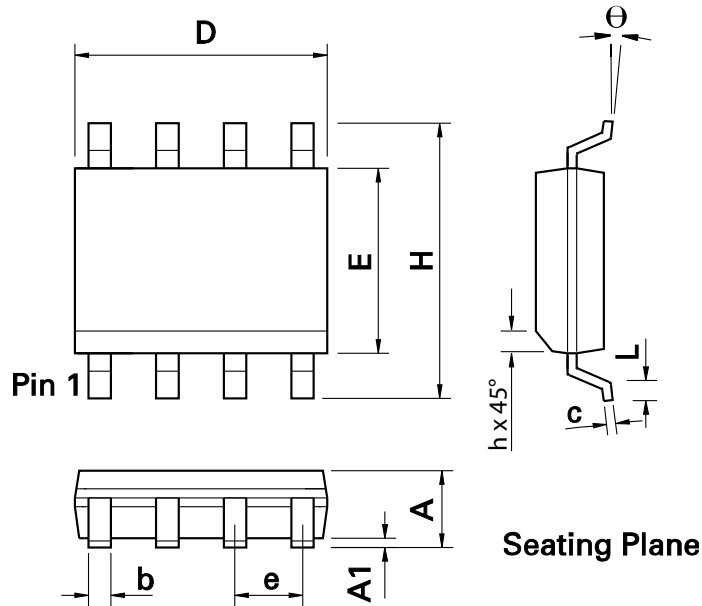
## Typical Characteristics - continued



## Test Circuits

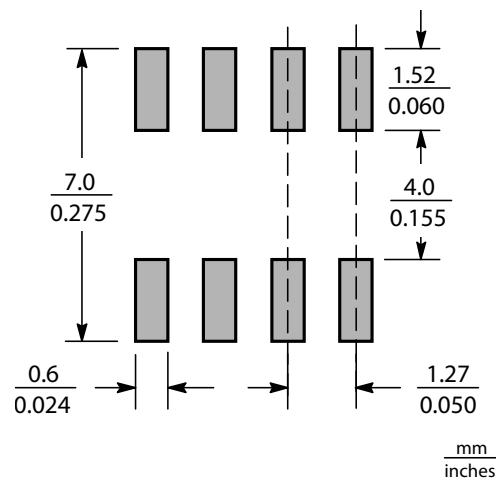


## Package Outline Dimensions



DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.053	0.069	1.35	1.75	e	0.050 BSC		1.27 BSC	
A1	0.004	0.010	0.10	0.25	b	0.013	0.020	0.33	0.51
D	0.189	0.197	4.80	5.00	c	0.008	0.010	0.19	0.25
H	0.228	0.244	5.80	6.20	θ	0°	8°	0°	8°
E	0.150	0.157	3.80	4.00	h	0.010	0.020	0.25	0.50
L	0.016	0.050	0.40	1.27	-	-	-	-	-

## Suggested Pad Layout



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